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form: A4mmXLc 1	1 2 FCconnection 1 2 FCconnection 1 MATERIAL: HOUSING: LCP CONTACT: COPPER ALLOY PR 2 PLATING: CONTACT: COPPER ALLOY PR 2 SOLDER BALL: (SEE TABLE) SOLDER BALL: (SEE TABLE) SOLDER BALL: (SEE TABLE) 3 MATED HEIGHT EFFECTED BY CUSTOMER'S POB PAD SIZE. 9 SSIDER BALL: SIZE THE RECID PROFILE, & SOLDER PATING, SOLDER REFLOW PROFILE, & SOLDER PASTE. 3 MATED HEIGHT EFFECTED BY CUSTOMER'S POB PAD SIZE. 9 PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE. 9 SATING, SOLDER REFLOW PROFILE, & SOLDER PASTE. 9 PLATING, SOLDER REFLOW THE REQUIREMENTS OF GG-1217-CORE. CENTRAL OFFICE ENVIRONMENT, (25 YEAR UFFE EXPECTANCY). THE CONTACT GEOMETRY IN THESE PRODUCT NUMBERS IS SPECIAL ASO. 9 FOR PROPERT APPLICATION FOLLOW FCI APPLICATION SOLDER BALLS WILL NOT SOLDER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDER BALLS SOLDER BALLS DUE TO A HICHER REFLOW TEMPERATURE. LEAD FREE PRODUCT MEETING SOLDER BALLS SOLDER BALLS DUE TO A HICHER SELEONER APPLICATION. REFERENCE FOR DUCT MEETING HERE FOROTION. 6 THIS PRODUCT MEET SUBDER MUNION DIRECTIVES AND OTHER COUNTRY REGULATION SECRETIVE IS DUERTREFIED IN CS-47-0004 PRODUCT MEETING THE DIRECTIVE IS DUERTREFIED IN THE LOT NO HEEN COUNTRY REGULATIONS AS DESCRIBED IN CS-47-0004 PRODUCT MEETING THE PROTONN. 6 THIS REVENTH CHARACTER POSITION. 7. 74388-A01, AND -A011F HAVE CUSTOMER SPECIAL AJ PLATING.	
2	PRODUCT NUMBER 74388-001 74388-001 74388-001 74388-001LF 74388-001LF 74388-001LF 74388-101LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-201LF 74388-401LF 74388-501LF	
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E	ACT PLATING (.38um) Au (.38um) Au (.38um) Au (.76um) Au (.76u	
	SnPb SnPb SnPb SnPb SnPb SnPb SnPb SnPb SnPb SnPb FRE SnPb SnPb FRE	- \)
4	L NOTES E 6 E 6 E 6 E 6 E 6 E 6 E 6 E 6	/

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